DATA SHEET

SKY67100-396LF: 1.2-3.0 GHz High Linearity, Active Bias Low-Noise Amplifier

Applications

- GSM, CDMA, WCDMA, and TD-SCDMA cellular infrastructure
- Ultra low-noise systems

Features

- Ultra Low Noise Figure: 0.71 dB @ 1.95 GHz
- Excellent input return loss > 20 dB
- High OIP3 performance: +34 dBm @ 1.95 GHz
- Adjustable supply current and gain
- Temperature and process-stable active bias
- Miniature DFN (8-pin, 2 x 2 mm) package (MSL1 @ 260 °C per JEDEC J-STD-020)

Skyworks Green™ products are compliant with all applicable legislation and are halogen-free. For additional information, refer to *Skyworks Definition of Green™*, document number SQ04-0074.

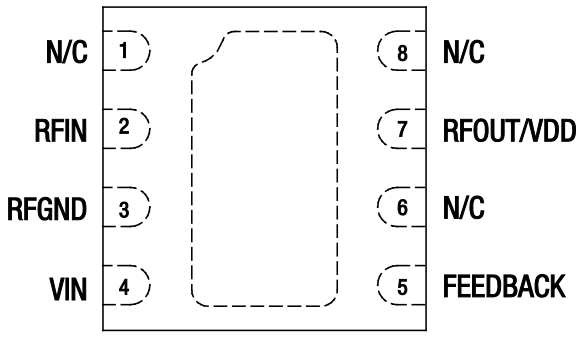


Figure 2. SKY67100-396LF Pinout – 8-Pin DFN (Top View)

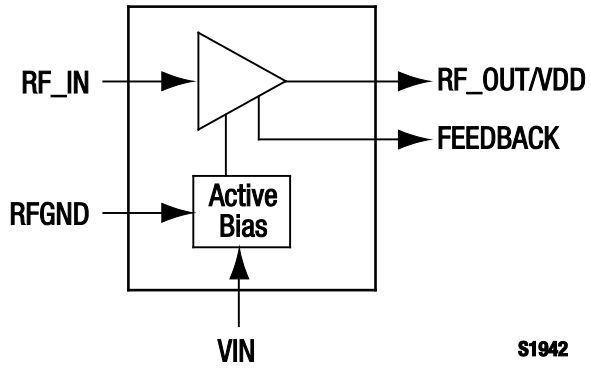


Figure 1. SKY67100-396LF Block Diagram

Description

The SKY67100-396LF is GaAs, pHEMT Low-Noise Amplifier (LNA) with an active bias and high linearity performance. The advanced GaAs pHEMT enhancement mode process provides excellent return loss, low noise, and high linearity performance.

The internal active bias circuitry provides stable performance over temperature and process variation. The device offers the ability to externally adjust supply current and gain. Supply voltage is applied to the RFOUT/VDD pin through an RF choke inductor. Pin 4 (VIN) should be connected to RFOUT/VDD through an external resistor to control the supply current. The RFIN and RFOUT/VDD pins should be DC blocked to ensure proper operation. Pin 5 (FEEDBACK) is connected through an RC network to externally adjust the gain of the device without affecting the Noise Figure (NF) of the LNA.

The SKY67100-396LF operates in the frequency range of 1.2 to 3.0 GHz with proper tuning. For lower frequency operation, the pin-compatible SKY67101-396LF should be used.

The LNA is manufactured in a compact, 2 x 2 mm, 8-pin Dual Flat No-Lead (DFN) package. A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

Table 1. SKY67100-396LF Signal Descriptions

Pin #	Name	Description	Pin #	Name	Description
1	N/C	No connection. May be connected to ground with no change in performance.	5	FEEDBACK	LNA external gain control. Connect to RFOUT using a series RD network.
2	RFIN	RF input. DC blocking capacitor required.	6	N/C	No connection. May be connected to ground with no change in performance.
3	RFGND	RF ground. Connect to ground through a capacitor.	7	RFOUT/VDD	RF output. Apply VDD through RF choke inductor. DC blocking capacitor required.
4	VIN	LNA supply current. Connect through series resistor to VDD.	8	N/C	No connection. May be connected to ground with no change in performance.

Table 2. SKY67100-396LF Absolute Maximum Ratings

Parameter	Symbol	Minimum	Typical	Maximum	Units
Supply voltage	V_{DD}			5.5	V
Supply current	I_{DD}			100	mA
RF input power	P_{IN}			+20	dBm
Storage temperature	T_{STG}	–65	+25	+125	°C
Operating temperature	T_A	–40	+25	+85	°C
Junction temperature	T_J			+150	°C

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

Thermal resistance = 80 °C/W @ 4 V bias.

***CAUTION**: Although this device is designed to be as robust as possible, Electrostatic Discharge (ESD) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times. The SKY67100-396LF is a Human Body Model (HBM) Class A ESD device.*

Electrical and Mechanical Specifications

The absolute maximum ratings of the SKY67100-396LF are provided in Table 2. Electrical specifications are provided in Table 3.

Typical performance characteristics of the SKY67100-396LF are illustrated in Figures 3 through 14.

Table 3. SKY67100-396LF Electrical Specifications (Note 1)
(V_{DD} = 4.0 V, I_{DD} = 56 mA, T_A = +25 °C, P_{IN} = –20 dBm, Characteristic Impedance [Z_O] = 50 Ω, Thermal Resistance = 80 °C/W, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typical	Max	Units
RF Specifications						
Noise Figure (Note 2)	NF	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		0.62 0.65 0.71	 1.00	dB dB dB
Small signal gain	|S21|	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz	17.3 17.0 16.6	18.3 18.0 17.6	19.3 19.0 18.6	dB dB dB
Input return loss	|S11|	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		30.4 25.3 20.6		dB dB dB
Output return loss	|S22|	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		11.6 12.4 12.7		dB dB dB
Reverse isolation	|S12|	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		43.0 43.1 43.3		dB dB dB
3rd Order Input Intercept Point	IIP3	Δf = 5 MHz, P_{IN} = –20 dBm/tone @ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		 +15.7 +16.1 +16.4		 dBm dBm dBm
3rd Order Output Intercept Point	OIP3	Δf = 5 MHz, P_{IN} = –20 dBm/tone @ 1.75 GHz @ 1.85 GHz @ 1.95 GHz	 +32.5	 +34.0 +34.3 +34.0		 dBm dBm dBm
1 dB Input Compression Point	IP1dB	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		+0.47 +0.65 +0.80		dBm dBm dBm
1 dB Output Compression Point	OP1dB	@ 1.75 GHz @ 1.85 GHz @ 1.95 GHz		+18.7 +18.4 +18.4		dBm dBm dBm
Stability	u1, u2	Up to 18 GHz, –40 °C to +85 °C		>1		–
DC Specifications						
Supply voltage	V_{DD}			4		V
Supply current	I_{DD}	Set with external resistor		56		mA

Note 1: Performance is guaranteed only under the conditions listed in this Table.

Note 2 Loss from the input SMA connector and Evaluation Board up to component C1 has been de-embedded from the NF measurement.

Typical Performance Characteristics

(V_{DD} = 4.0 V, I_{DD} = 56 mA, T_A = +25 °C, P_{IN} = –20 dBm, Characteristic Impedance [Z_O] = 50 Ω, Thermal Resistance = 80 °C/W, Unless Otherwise Noted)

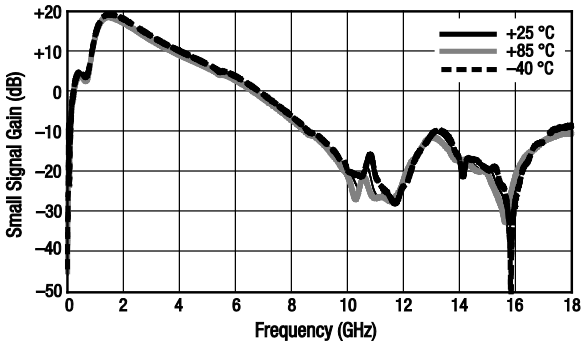


Figure 3. Broadband Gain Response vs Frequency

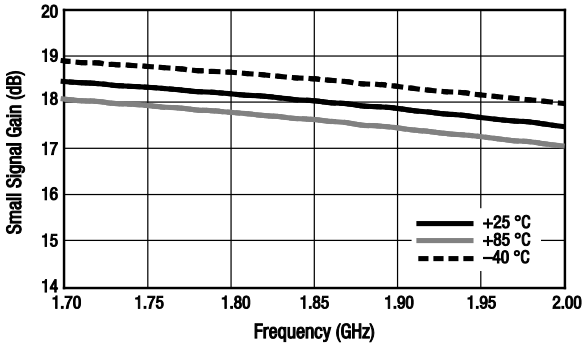


Figure 4. Narrowband Gain Response vs Frequency

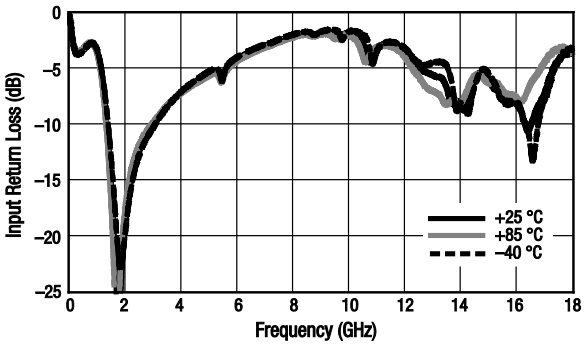


Figure 5. Broadband Input Return Loss vs Frequency

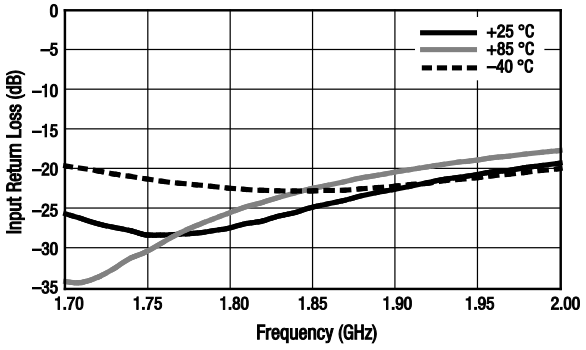


Figure 6. Narrowband Input Return Loss vs Frequency

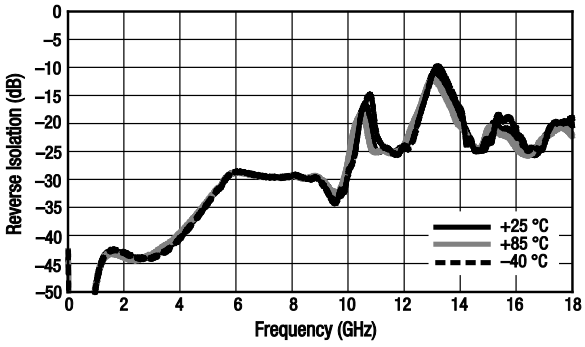


Figure 7. Broadband Reverse Isolation vs Frequency

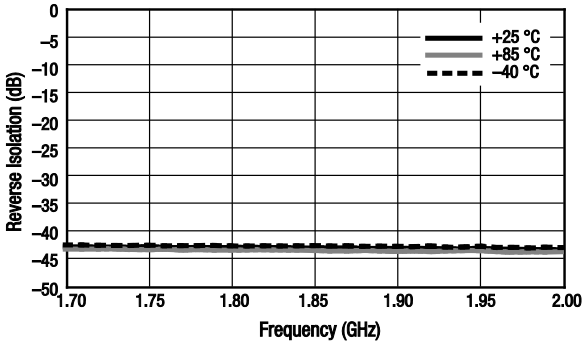


Figure 8. Narrowband Reverse Isolation vs Frequency

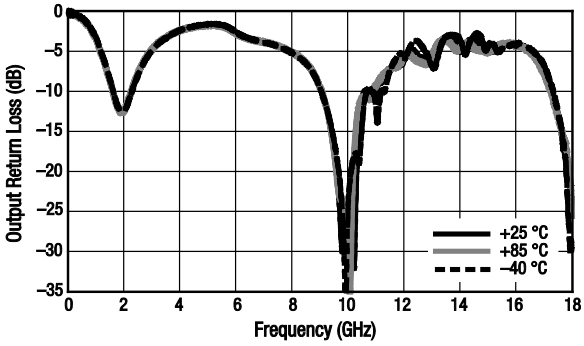


Figure 9. Broadband Output Return Loss vs Frequency

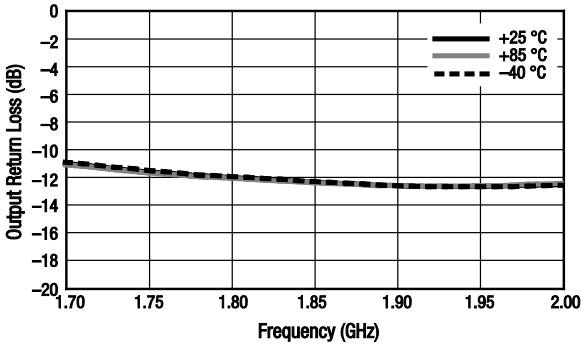


Figure 10. Narrowband Output Return Loss vs Frequency

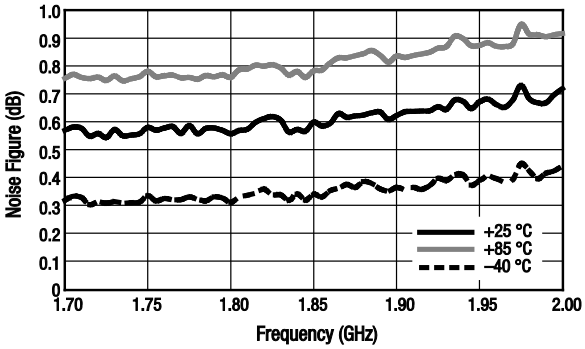


Figure 11. Noise Figure vs Frequency

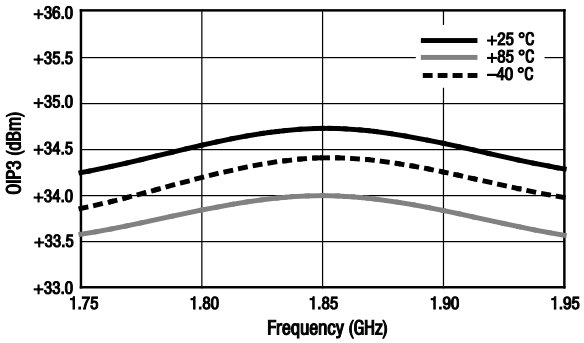


Figure 12. OIP3 vs Frequency
(P_{IN} = –20 dBm, Spacing = 5 MHz)

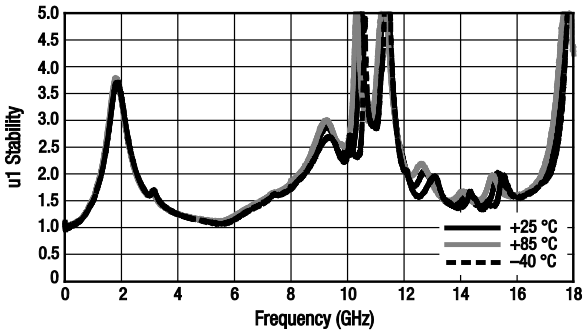


Figure 13. u1 Stability vs Frequency

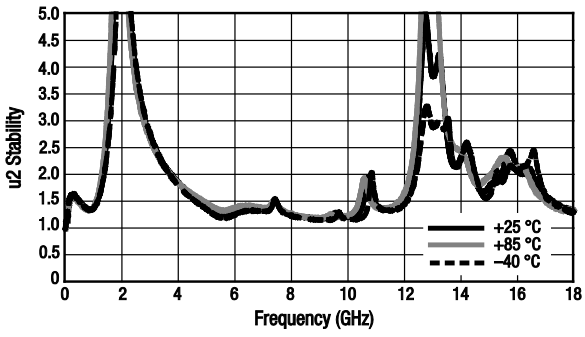


Figure 14. u2 Stability vs Frequency

Evaluation Board Description

The SKY67100-396LF Evaluation Board is used to test the performance of the SKY67100-396LF LNA. An assembly drawing for the Evaluation Board is shown in Figure 15. An Evaluation Board schematic diagram is provided in Figure 16. Table 4 provides the Bill of Materials (BOM) list for Evaluation Board components.

The test board uses a 10 mil Rogers 4350B substrate on a 50 mil FR4 supporting substrate. The Rogers 4350B material was selected for the RF circuit because of its low dielectric constant (ε_r) and low ε_r variation over temperature for the best possible noise performance.

Package Dimensions

The PCB layout footprint for the SKY67100-396LF is provided in Figure 17. Typical case markings are shown in Figure 18. Package dimensions for the 8-pin DFN are shown in Figure 19, and tape and reel dimensions are provided in Figure 20.

Package and Handling Information

Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

THE SKY67100-396LF is rated to Moisture Sensitivity Level 1 (MSL1) at 260 °C. It can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note, *Solder Reflow Information*, document number 200164.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.

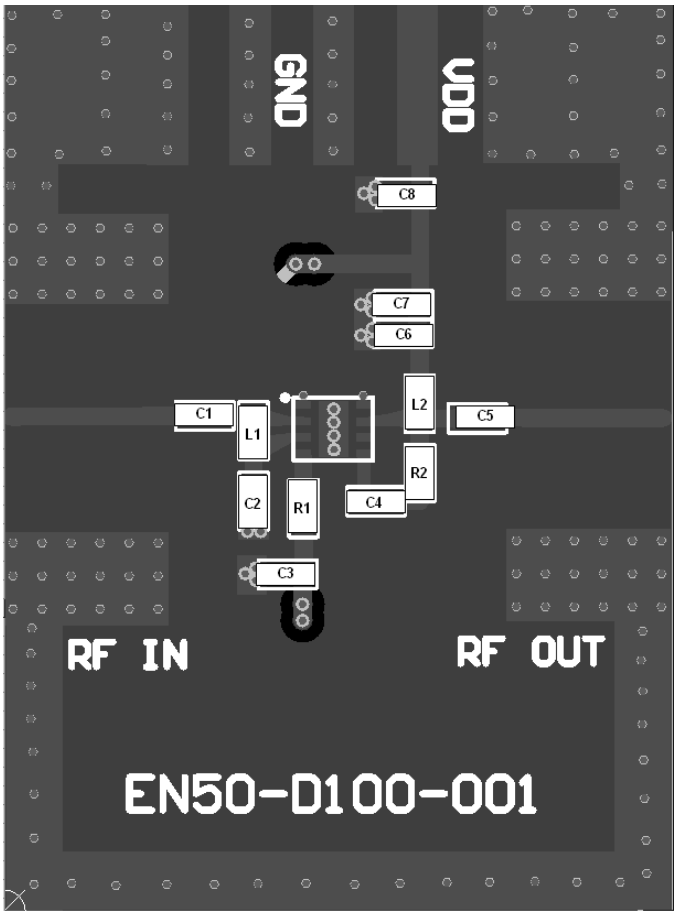


Figure 15. SKY67100-396LF Evaluation Board Assembly Diagram

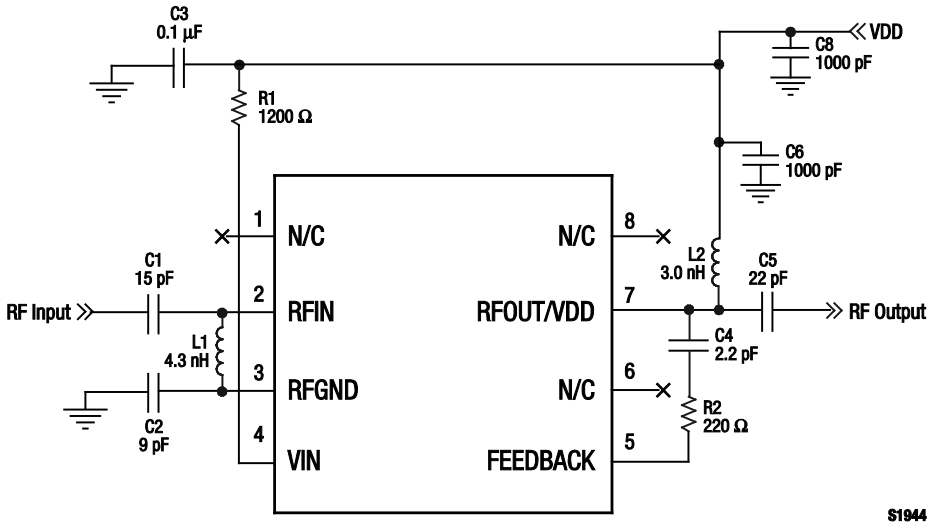


Figure 16. SKY67100-396LF Evaluation Board Schematic

Table 4. SKY67100-396LF Evaluation Board Bill of Materials

Component	Value	Size	Manufacturer
C1	15 pF	SMT 0402	Murata GJM
C2	9 pF	SMT 0402	Murata GJM
C3	0.1 µF	SMT 0402	Murata GRM
C4	2.2 pF	SMT 0402	Murata GJM
C5	22 pF	SMT 0402	Murata GRM
C6	1000 pF	SMT 0402	Murata GRM
C7	Do not populate		
C8	1000 pF	SMT 0402	Murata GRM
L1	4.3 nH	SMT 0402	Coilcraft HP
L2	3.0 nH	SMT 0402	TDK MLG
R1	1200 Ω	SMT 0402	Panasonic
R2	220 Ω	SMT 0402	Panasonic

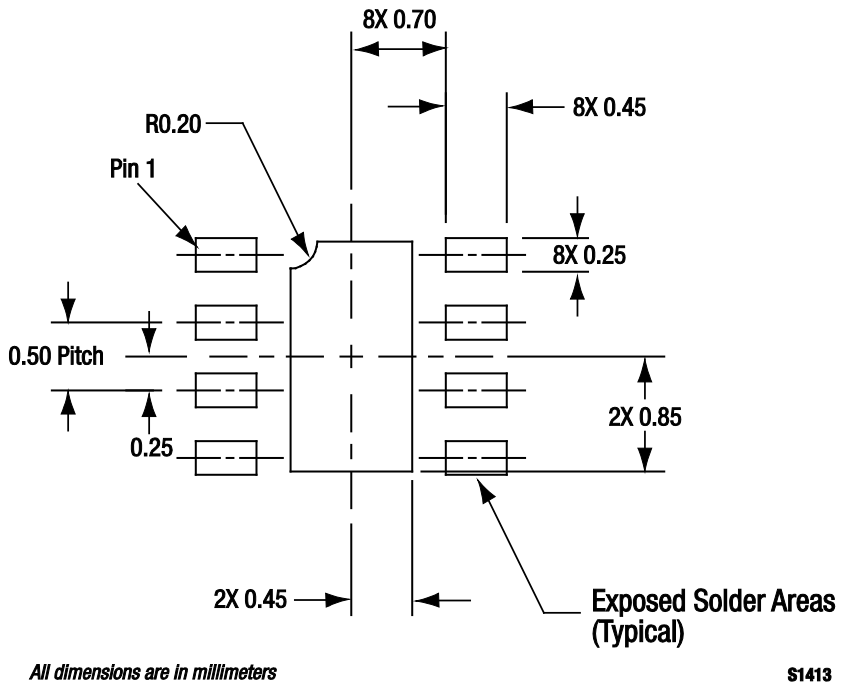


Figure 17. SKY67100-396LF PCB Layout Footprint
(Top View)

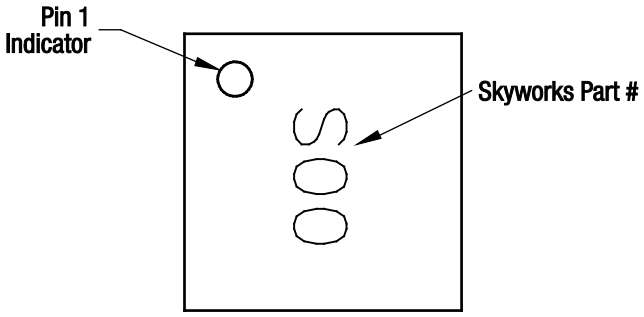
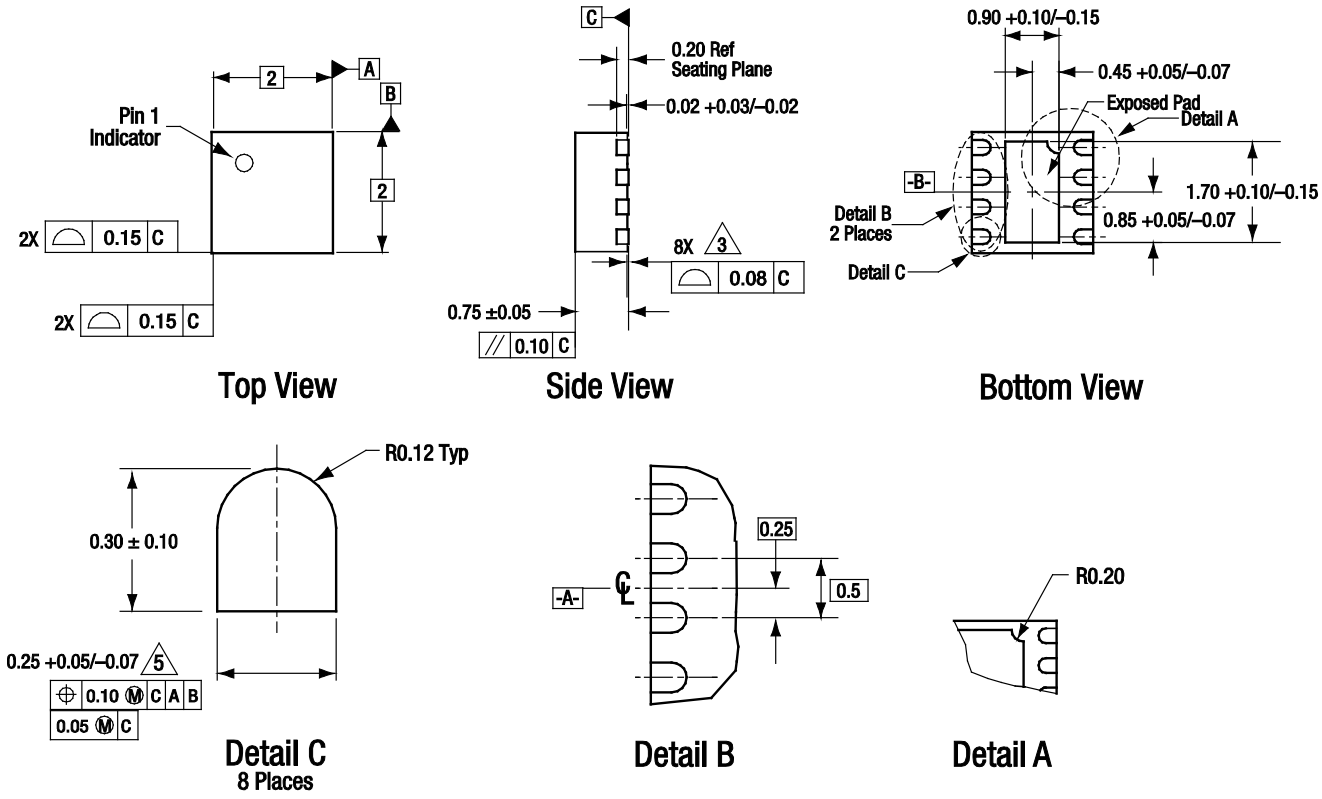


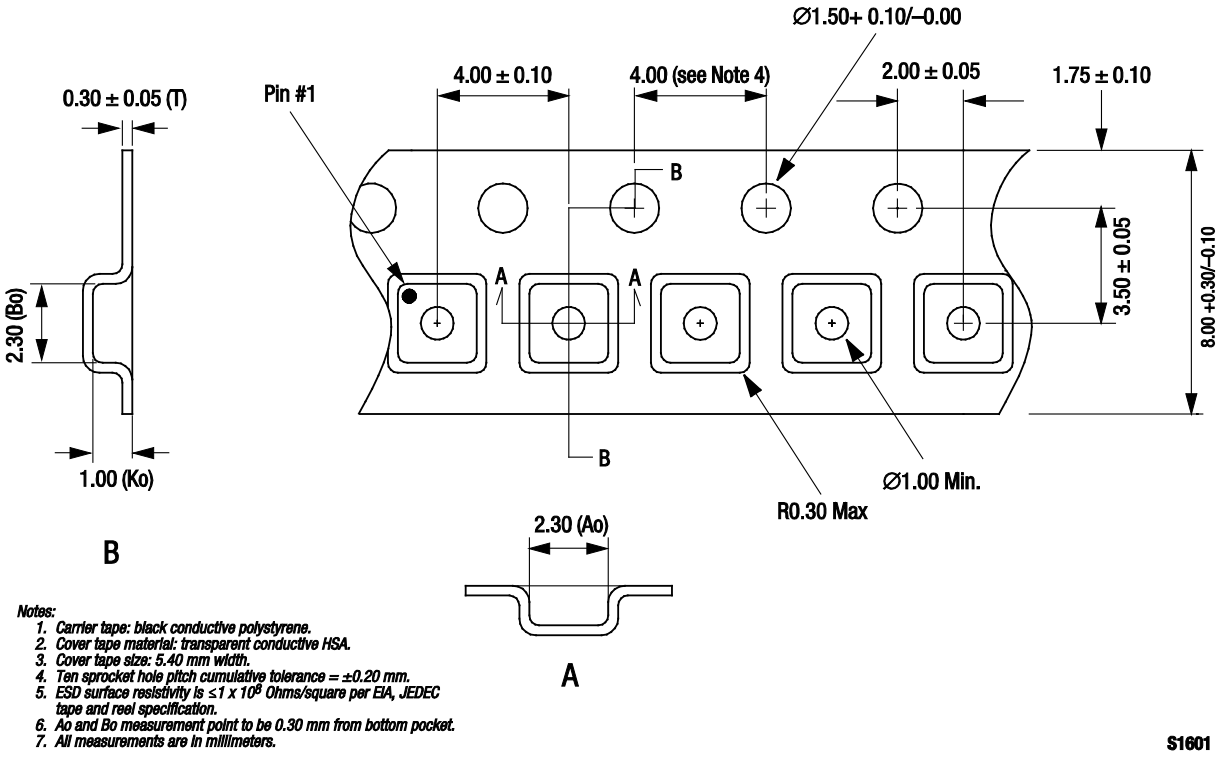
Figure 18. Typical Case Markings
(Top View)



All measurements are in millimeters.
Dimensioning and tolerancing according to ASME Y14.5M-1994.
Coplanarity applies to the exposed heat sink slug as well as the terminals..
Plating requirement per source control drawing (SCD) 2504.
Dimension applies to metalized terminal and is measured between 0.15 mm and 0.30 mm from terminal tip.

S1945

Figure 19. SKY67100-396LF 8-Pin DFN Package Dimensions



Notes:
1. *Carrier tape: black conductive polystyrene.*
2. *Cover tape material: transparent conductive HSA.*
3. *Cover tape size: 5.40 mm width.*
4. *Ten sprocket hole pitch cumulative tolerance = ±0.20 mm.*
5. *ESD surface resistivity is ≤1 x 10^9 Ohms/square per EIA, JEDEC tape and reel specification.*
6. *Ao and Bo measurement point to be 0.30 mm from bottom pocket.*
7. *All measurements are in millimeters.*

Figure 20. SKY67100-396LF Tape and Reel Dimensions

Ordering Information

Model Name	Manufacturing Part Number	Evaluation Board Part Number
SKY67100-396LF LNA	SKY67100-396LF	SKY67100-396LF-EVB